/ Descriptions

N ॅ TO-220 ṂṂ Ŀ ʃ ѽ Ẓ ৭

N-Channel MOSFET in a TO-220 Plastic Package.

/ Features

V_{DS}=200V ψ I_D=18A ψ V_{GS}=±20V

$R_{DS(on)}$@10V≤170mΩ(Type.115mΩ)

$R_{DS(on)}$@6V≤200mΩ(Type.130mΩ)

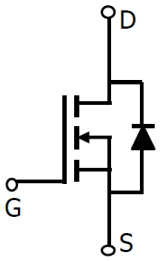
ṇ ғ β HF Product.

/ Applications

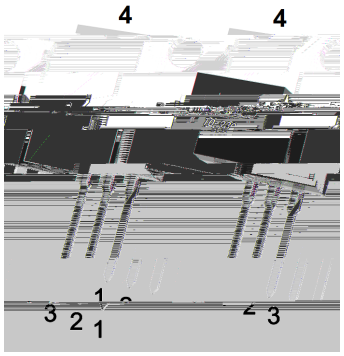
ﻝ ﻤ ق ڈ Â ԋ 0HG Ẓ ғ

Networking,Load Switch,LED applications.

/ Equivalent Circuit



/ Pinning



PIN1 χ G PIN 2 4 χ D PIN 3 χ S

/ Marking

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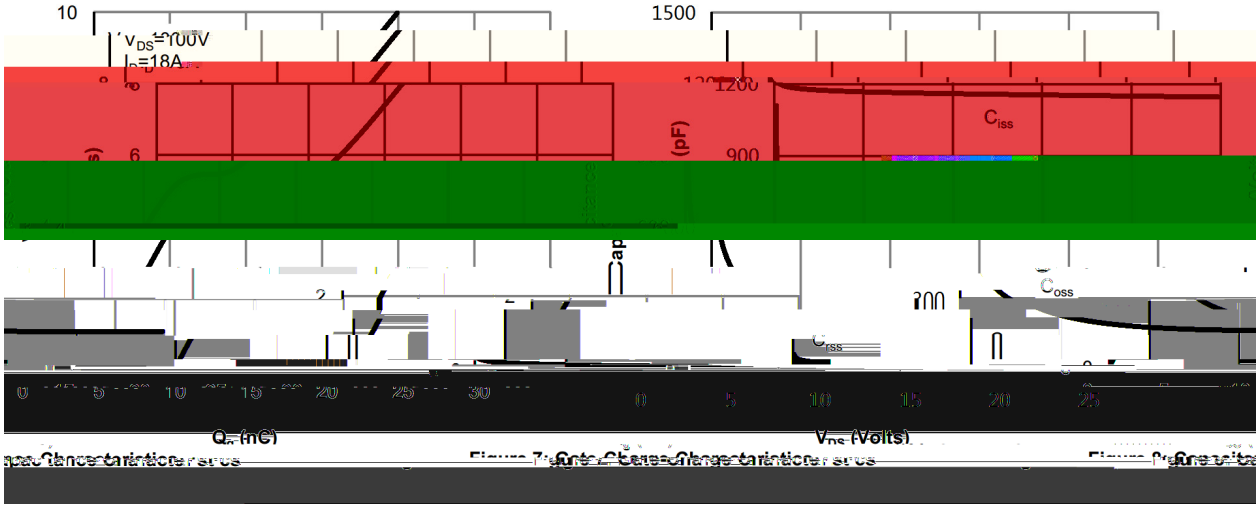
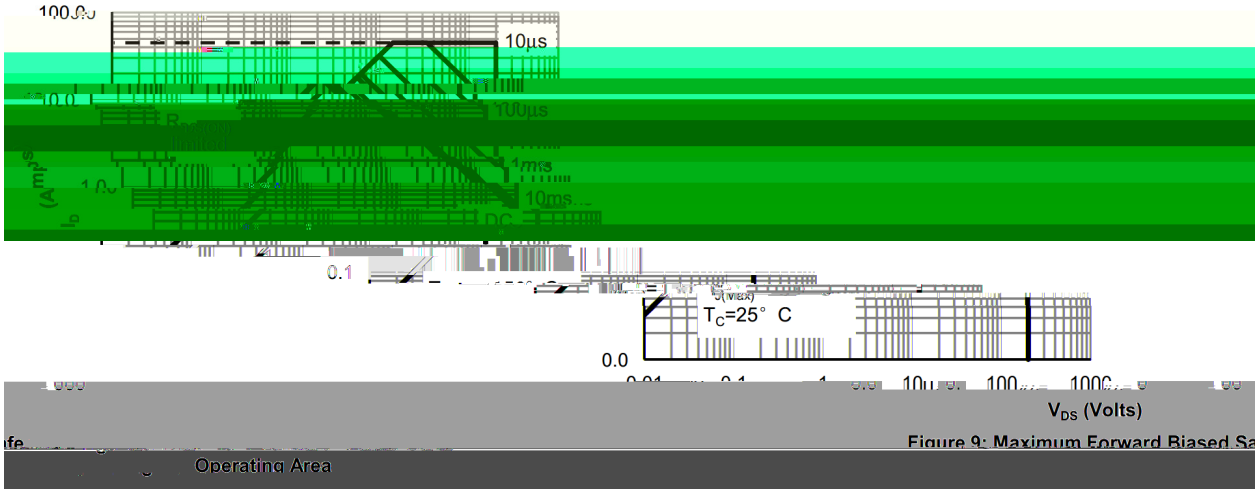
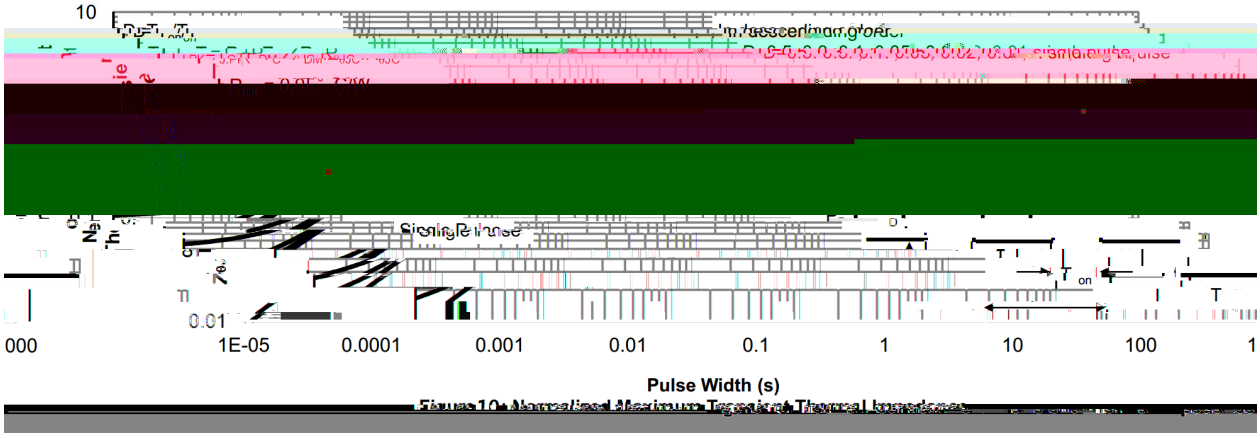
See Marking Instructions.

v ̈Ω Parameter	ϒ N Symbol	⅄ ;ǂ ʇ Test Conditions	ѡ ṇ Ө Min	Ɛ ʒ Ө Typ	ѡ ᶻ Ө Max	ᗡ Ꮒ Unit
Turn-On Delay Time	$t_{d(on)}$			11.7		
Turn-On Rise Time	t_r	V_{GS}=10V V_{DS}=75V R_{GEN}=3Ϝ		3.5		ns

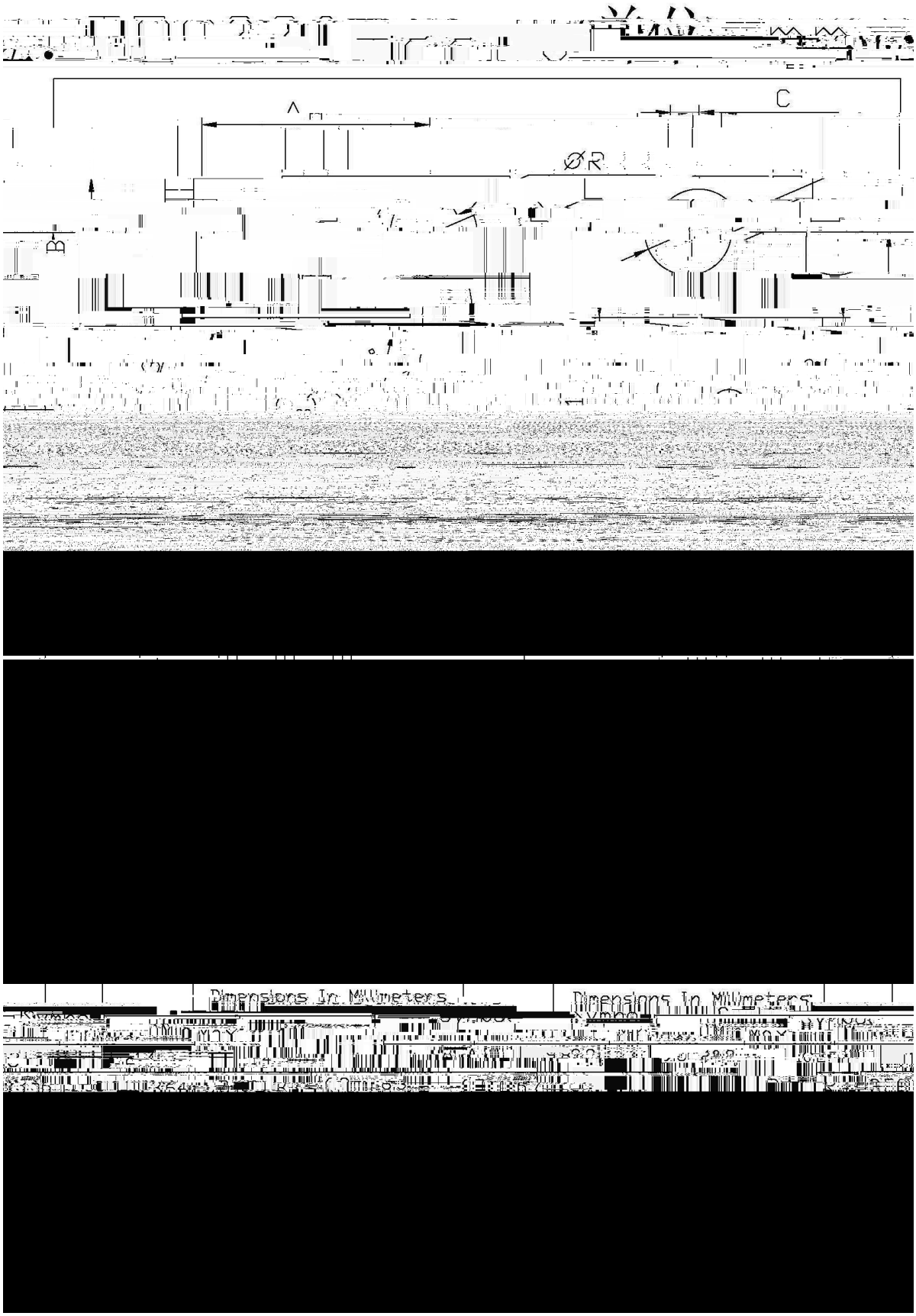
/ Electrical Characteristic Curve



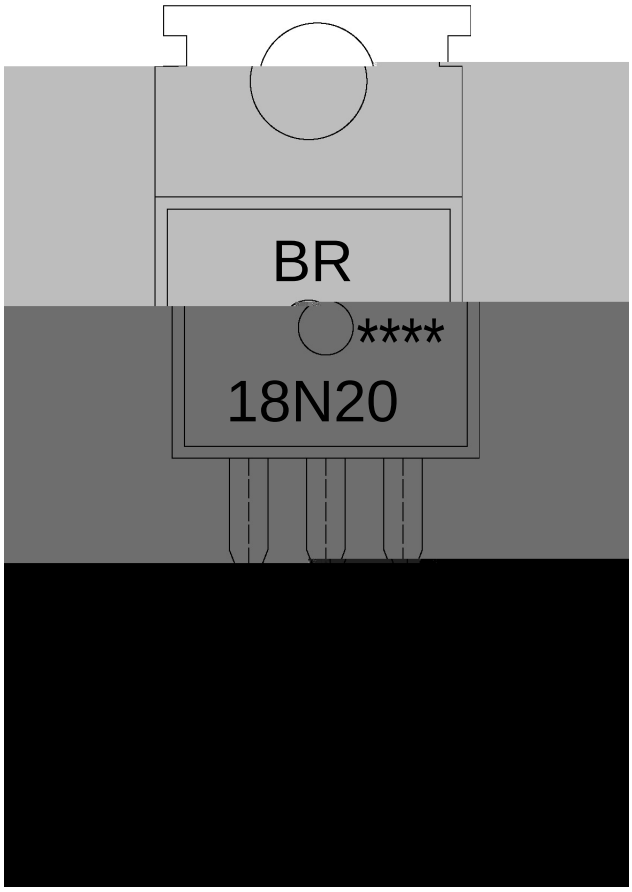




/ Package Dimensions



/ Marking Instructions



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4 ; Q53 χ	ѭ ʒ ᴺ Ꮁ
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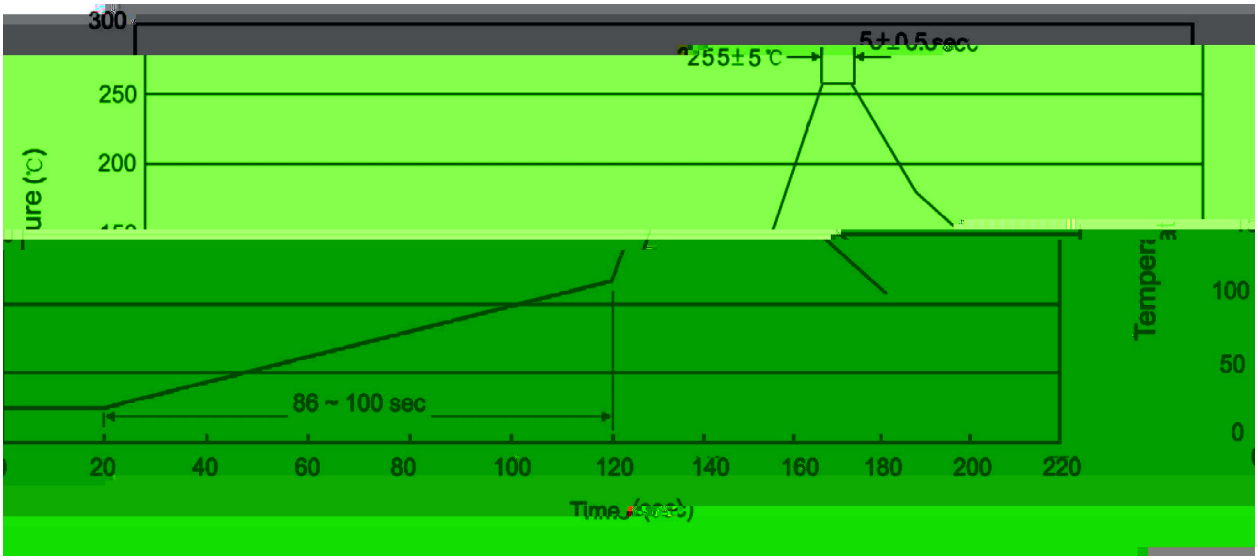
Note:

BR:	Company Code
18N20:	Product Type
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ë □ ỷ 255 ° 5 ł ı ˋH ڑ ˋY ﾊ ㎞ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ɔ ﻉ ỷ ㎞ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ł	ˋH ڑ χ 10 ° 1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

ˇQ ţ ｙ Ł / BULK